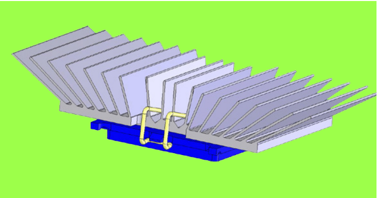
ATS ADVANCED THERMAL SOLUTIONS, INC.
Innovations in Thermal Management®

HEAT SINKS

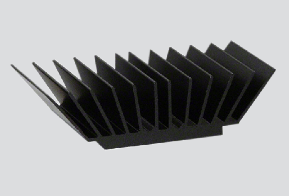
DEVICE SPECIFIC

- Custom cooling solutions for Flip-Chip Processors, Linux Board Support Packages (BSPs) & Integrated Communications Processors
- High performance maxiFLOW™ and straight fin heat sink designs with maxiGRIP™ attachment
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes to be drilled in the PCB
- Comes pre-assembled with high performance, phase change, thermal interface material

ASSEMBLY

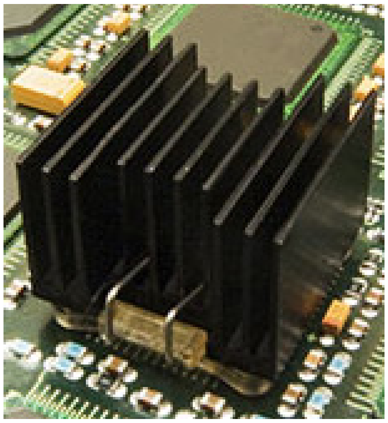


Flip-Chip
PROCESSORS

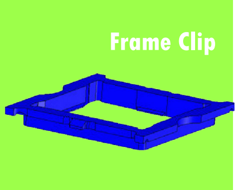


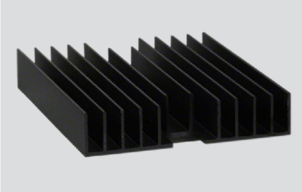
Specifically designed for
FREESCALE

BSPs
LINUX BOARD
SUPPORT PACKAGES

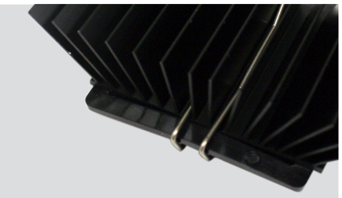


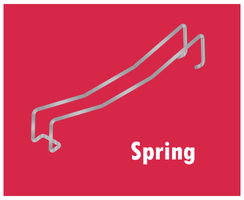
INTEGRATED COMMUNICATIONS
PROCESSORS





maxiGRIP™





For further technical information, call 781.769.2800, email ats-hq@qats.com or visit qats.com